



60V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} MAX	I _D T _C = +25°C	
60V	40mΩ @ V _{GS} = 10V	20A	
000	$58m\Omega @ V_{GS} = 4.5V$	16A	

Features

- Low Input Capacitance
- Low On-Resistance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

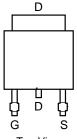
- DC-DC Converters
- **Power Management Functions**
- Backlighting

Mechanical Data

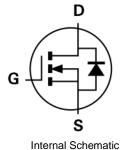
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e3)
- Weight: 0.33 grams (Approximate)







Top View



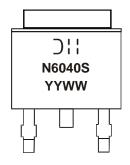
Ordering Information (Note 5)

Part Number	Case	Packaging	
DMN6040SK3Q-13	TO252 (DPAK)	2,500/Tape & Reel	

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



Oll =Manufacturer's Marking N6040S = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 18 = 2018) WW = Week Code (01 to 53)



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	60	V
Gate-Source Voltage	V_{GSS}	±20	V
Continuous Drain Current (Note 6) V _{GS} = 10V	I _D	20 13	А
Maximum Body Diode Forward Current (Note 6)	I _S	4	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	30	Α
Avalanche Current (Note 7)	I _{AS}	14.2	Α
Avalanche Energy (Note 7)	E _{AS}	10	mJ

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 6)	$T_C = +25^{\circ}C$	C	42	W
Total Power Dissipation (Note 6)	T _C = +100°C	P _D	17	
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	44	°C/W	
Thermal Resistance, Junction to Case (Note 6)	$R_{ heta JC}$	3	10/00	
Operating and Storage Temperature Range	$T_{J_i}T_{STG}$	-55 to +150	°C	

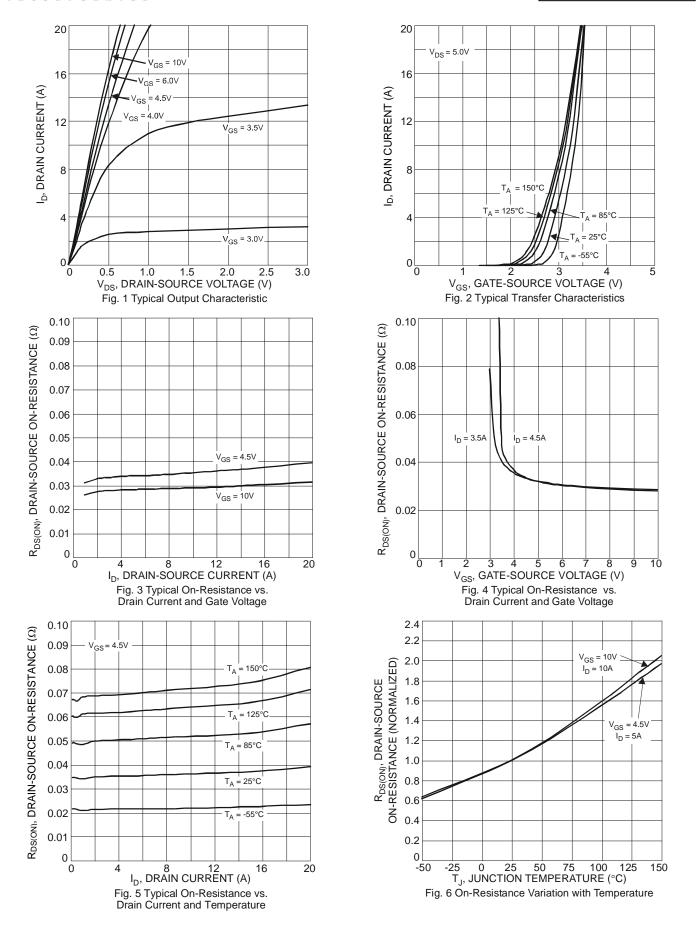
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)				•	•		
Drain-Source Breakdown Voltage	BV _{DSS}	60		_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 60V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	1		3	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	Б		30	40	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Diam-Source Off-Resistance	R _{DS(ON)}	_	35	58	11177	$V_{GS} = 4.5V, I_D = 12A$	
Diode Forward Voltage	V_{SD}	_	0.7	1.2	V	$V_{GS} = 0V$, $I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	1	1,287	_		$V_{DS} = 25V, V_{GS} = 0V$ f = 1.0MHz	
Output Capacitance	Coss		57	_	pF		
Reverse Transfer Capacitance	C _{rss}		44	_			
Gate Resistance	Rg	_	1.2	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$	
Total Gate Charge (V _{GS} = 10V)	Q_g		22.4	_			
Total Gate Charge (V _{GS} = 4.5V)	Q_g		10.4	_	nC	Vps = 30V. Ip = 4.3A	
Gate-Source Charge	Q_{gs}	_	4.9	_	nc nc	$I_{DS} = 30V, I_{D} = 4.3A$	
Gate-Drain Charge	Q_{gd}	_	3.0	_			
Turn-On Delay Time	t _{D(ON)}	_	6.6	_			
Turn-On Rise Time	t _R	_	8.1	_		$V_{GS} = 10V, V_{DD} = 30V, R_G = 6\Omega,$	
Turn-Off Delay Time	t _{D(OFF)}		20.1	_	ns	$I_D = 4.3A$	
Turn-Off Fall Time	t _F	_	4.0	_			
Body Diode Reverse Recovery Time	t _{RR}		18	_	ns	I _S = 4.3A, dl/dt = 100A/μs	
Body Diode Reverse Recovery Charge	Q _{RR}		11.9	_	nC	$I_S = 4.3A$, $dI/dt = 100A/\mu s$	

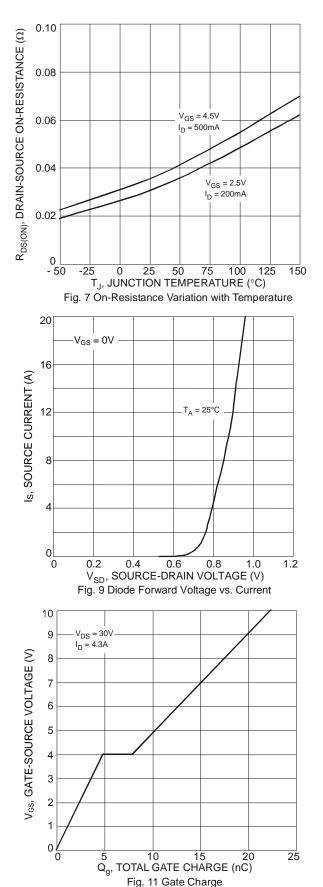
Notes:

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout.
- 7. UIS in production with L = 0.1 mH, $T_J = +25 ^{\circ}\text{C}$.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.









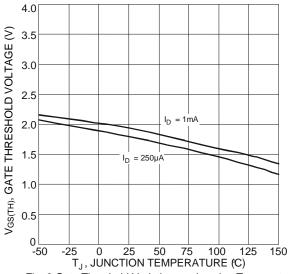
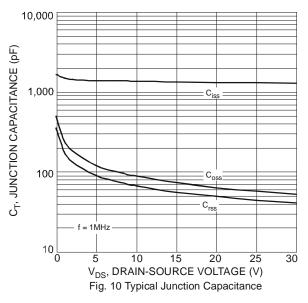
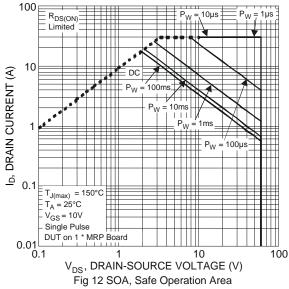


Fig. 8 Gate Threshold Variation vs. Junction Temperature



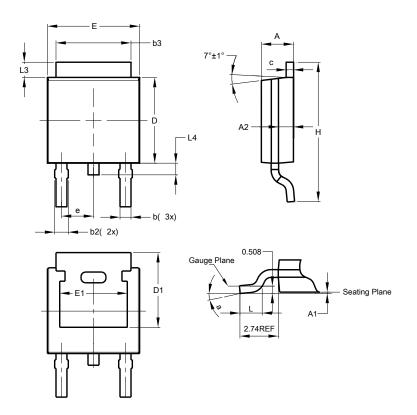




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)

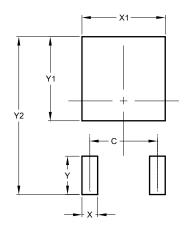


TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	-		
е	-	-	2.286		
Е	6.45	6.70	6.58		
E1	4.32	-	-		
Ξ	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)		
С	4.572		
Х	1.060		
X1	5.632		
Y	2.600		
Y1	5.700		
Y2	10.700		



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